

DSMO No.: M4065.0374/P374
Micron No.: 99-1057

ABSTRACT

Disclosed is a method for forming a semiconductor assembly and the resulting assembly in which a flowable adhesive material which secures a die to a support and does not form an adhesive fillet. A flowable adhesive is deposited between the die and support so that it covers about 5 50 to about 90 percent of the bottom surface area of the die after the die is mounted to the support. The reduced surface coverage area prevents formation of an adhesive fillet.

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